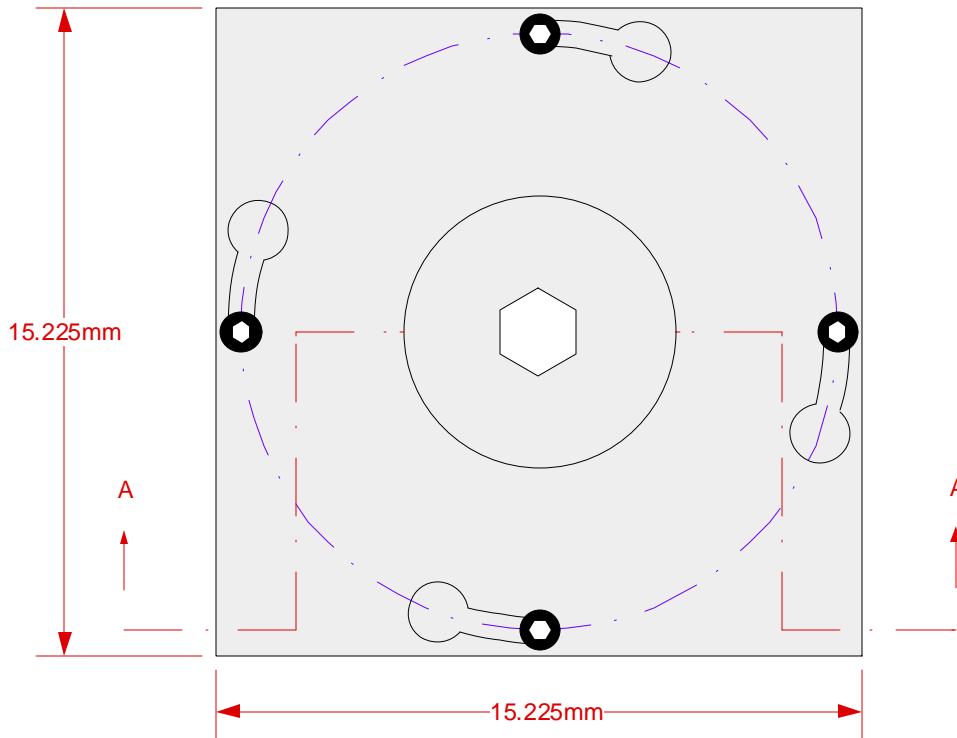


Top View

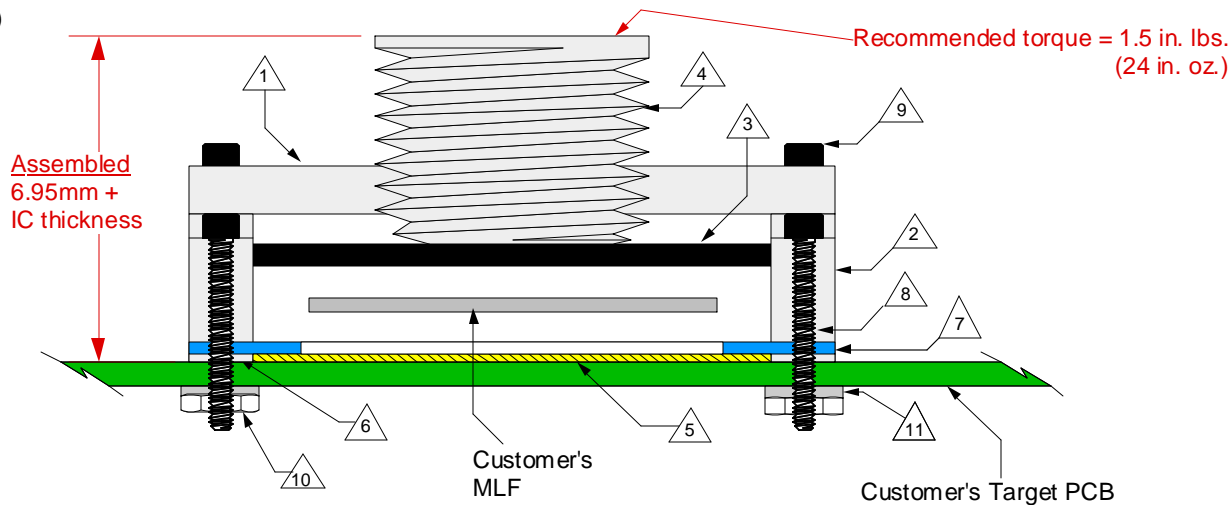


GHz MLF Socket - Direct mount, solderless


Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- IC guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



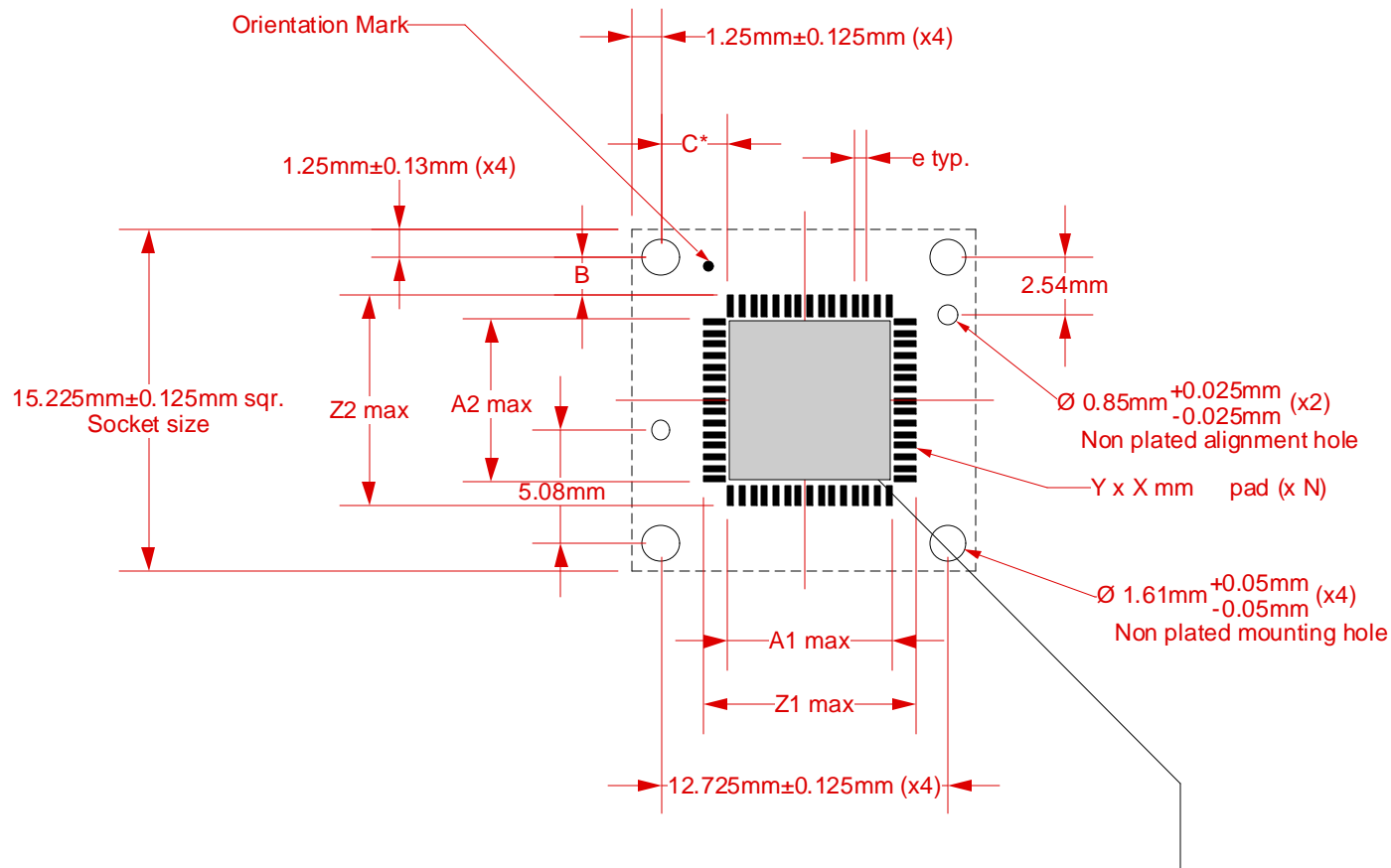
- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 3mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 1.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 3mm.
- 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 6 Elastomer Guide: Cirlex Thickness = 0.475mm.
- 7 IC (MLF) Guide: Torlon 4203
- 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

	SG-MLF-7008 Drawing	Status: Released	Scale: -	Rev: H
	© 2002 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 10/22/02
		File: SG-MLF-7008 Dwg.mcd	Modified: 11/11/14	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**



**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.


Target PCB Recommendations

Total thickness: 1.6mm min.

Plating: Gold or Solder finish

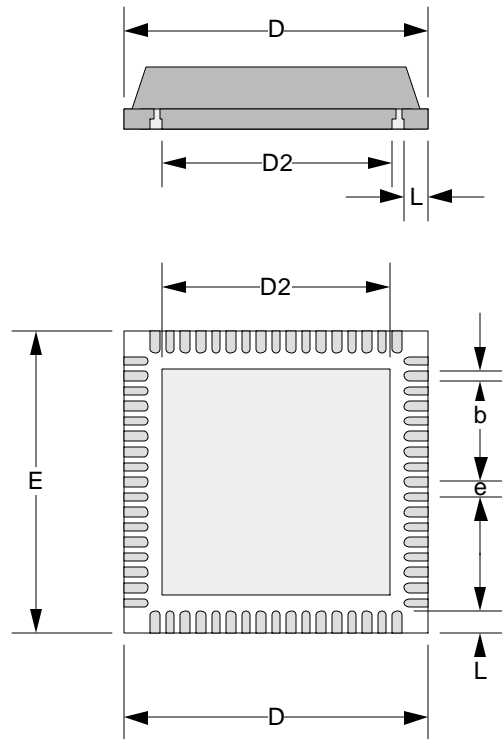
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

	SG-MLF-7008 Drawing	Status: Released	Scale: 3:1	Rev: H
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		File: SG-MLF-7008 Dwg.mcd	Modified: 11/11/14	

Package Code	C	B	Z1max	A1max	Z2max	A2 max	e	X	Y	N	Thermal Pad Recommendations
MLF76A	2.89	1.68	9.36	7.45	9.36	7.45	0.4	0.25	0.96	76	6.84 x 6.84
MLF60A	2.97	1.68	9.36	7.28	9.36	7.28	0.5	0.28	0.94	60	7.08 x 7.08
MLF64A	2.72	1.68	9.36	7.78	9.36	7.78	0.5	0.28	0.69	64	7.58 x 7.58
MLF48A	2.81	1.45	9.82	7.6	9.82	7.6	0.65	0.45	1.06	48	7.5 x 7.5
MLF44C	3.18	1.68	9.36	6.87	9.36	6.87	0.65	0.37	1.06	44	6.84 x 6.84
MLF24D	3.2	1.68	9.36	7.11	9.36	7.11	1.27	0.76	1.06	24	5.5 x 5.5
MLF36B	3.2	1.68	9.36	6.82	9.36	6.82	0.8	0.42	1.06	36	6.84 x 6.84

All dimensions are in mm.



Package Code	e	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
MLF76A	0.4	8.85	9.15	8.85	9.15	0.15	0.25	0.4	0.6	5.45	76
MLF60A	0.5	8.85	9.15	8.85	9.15	0.18	0.3	0.5	0.75	7.18	60
MLF64A	0.5	8.85	9.15	8.85	9.15	0.18	0.3	0.3	0.5	7.68	64
MLF48A	0.65	8.90	9.10	8.90	9.10	0.35	0.45	0.35	0.45	7.50	48
MLF44C	0.65	8.85	9.15	8.85	9.15	0.23	0.35	0.5	0.75	6.94	44
MLF24D	0.65	8.85	9.15	8.85	9.15	0.55	0.65	0.6	0.8	5.5	24
MLF36B	0.8	8.85	9.15	8.85	9.15	0.28	0.4	0.5	0.75	6.94	36

SG-MLF-7008 Drawing

Status: Released

Scale: 3:1

Rev: H



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